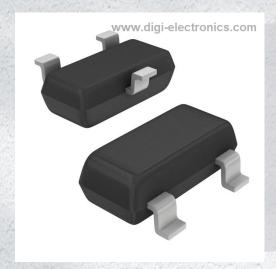


NTR4171PT3G Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number NTR4171PT3G-DG

Manufacturer onsemi

Manufacturer Product Number NTR4171PT3G

Description MOSFET P-CH 30V 2.2A SOT23-3

Detailed Description P-Channel 30 V 2.2A (Ta) 480mW (Ta) Surface Mou

nt SOT-23-3 (TO-236)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

Manufacturer Product Number: Manufacturer: NTR4171PT3G onsemi Product Status: Series: Obsolete FET Type: Technology: P-Channel MOSFET (Metal Oxide) Drain to Source Voltage (Vdss): Current - Continuous Drain (Id) @ 25°C: 30 V 2.2A (Ta) Drive Voltage (Max Rds On, Min Rds On): Rds On (Max) @ Id, Vgs: 2.5V, 10V 75mOhm @ 2.2A, 10V Vgs(th) (Max) @ Id: Gate Charge (Qg) (Max) @ Vgs: 1.4V @ 250µA 15.6 nC @ 10 V Vgs (Max): Input Capacitance (Ciss) (Max) @ Vds: ±12V 720 pF @ 15 V FET Feature: Power Dissipation (Max): 480mW (Ta) Operating Temperature: Mounting Type: -55°C ~ 150°C (TJ) **Surface Mount** Supplier Device Package: Package / Case: SOT-23-3 (TO-236) TO-236-3, SC-59, SOT-23-3 Base Product Number: NTR417

Environmental & Export classification

Moisture Sensitivity Level (MSL):	REACH Status:
1 (Unlimited)	REACH Unaffected
ECCN:	HTSUS:
EAR99	8541.21.0095

MOSFET – Power, Single, P-Channel, SOT-23

-30 V, -3.5 A

Features

- Low R_{DS(on)} at Low Gate Voltage
- Low Threshold Voltage
- High Power and Current Handling Capability
- This is a Pb-Free Device

Applications

- Load Switch
- Optimized for Battery and Load Management Applications in Portable Equipment like Cell Phones, PDA's, Media Players, etc.

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit	
Drain-to-Source Voltage			V_{DSS}	-30	V	
Gate-to-Source Voltage			V _{GS}	±12	V	
Continuous Drain	Steady	T _A = 25°C		-2.2		
Current (Note 1)	State	T _A = 85°C	I _D	-1.5	Α	
	t ≤ 5 s	T _A = 25°C		-3.5		
Power Dissipation	Steady State	T _A = 25°C	P _D	0.48	W	
(Note 1)						
	t ≤ 5 s			1.25		
Pulsed Drain Current $t_p = 10 \mu s$			I _{DM}	-15.0	Α	
Operating Junction and Storage Temperature			T _J , T _{stg}	–55 to 150	ô	
Source Current (Body Diode)			I _S	-1.0	Α	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	260	°C/W
Junction-to-Ambient - t ≤ 10 s (Note 1)	$R_{\theta JA}$	100	

 Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)

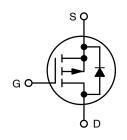


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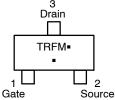
V _{(BR)DSS} R _{DS(on)} MAX		I _D MAX
-30 V	75 mΩ @ –10 V	-2.2 A
	110 mΩ @ –4.5 V	–1.8 A
	150 mΩ @ -2.5 V	-1.0 A

P-CHANNEL MOSFET



MARKING DIAGRAM/ PIN ASSIGNMENT 3 Drain

2 SOT-23 CASE 318 STYLE 21



TRF = Specific Device Code

M = Date Code ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NTR4171PT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
NTR4171PT3G	SOT-23 (Pb-Free)	10000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MOSFET ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$	-30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I_D = -250 μ A, Reference to 25°C		24		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V}, V_{DS} = -24 \text{ V}, T_J = 25^{\circ}\text{C}$ $V_{GS} = 0 \text{ V}, V_{DS} = -24 \text{ V}, T_J = 85^{\circ}\text{C}$			-1.0 -5.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			±0.1	μΑ
ON CHARACTERISTICS (Note 3)				•		· •
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = -250 \mu A$	-0.7	-1.15	-1.4	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J			3.5		mV/°0
Drain-to-Source On-Resistance	R _{DS(on)}	$V_{GS} = -10 \text{ V}, I_D = -2.2 \text{ A}$		50	75	mΩ
		$V_{GS} = -4.5 \text{ V}, I_D = -1.8 \text{ A}$		60	110	
		$V_{GS} = -2.5 \text{ V}, I_D = -1.0 \text{ A}$		90	150	1
Forward Transconductance	9FS	$V_{DS} = -5.0 \text{ V}, I_D = -2.2 \text{ A}$		7.0		S
CHARGES, CAPACITANCES AND GATE R	ESISTANCE					
Input Capacitance	C _{iss}			720		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = -15 \text{ V}$		95		1
Reverse Transfer Capacitance	C _{rss}	VDS = -13 V		65		1
Total Gate Charge	Q _{G(TOT)}			15.6		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = -10 V, V _{DS} = -15 V,		0.7		1
Gate-to-Source Charge	Q _{GS}	$I_D = -3.5 \text{A}$		1.6		
Gate-to-Drain Charge	Q_{GD}			2.6		1
Total Gate Charge	Q _{G(TOT)}			7.4		nC
Threshold Gate Charge	Q _{G(TH)}	Vce = -4.5 V. Vce = -15 V.		0.7		1
Gate-to-Source Charge	Q _{GS}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -15 \text{ V},$ $I_{D} = -3.5 \text{ A}$		1.6		
Gate-to-Drain Charge	Q_{GD}			2.6		
Gate Resistance	R _G			6.1		Ω
SWITCHING CHARACTERISTICS, V _{GS} = 4.	5 V (Note 4)		•	•		
Turn-On Delay Time	t _{d(on)}			8.0		ns
Rise Time	t _r	V _{GS} = -10 V, V _{DS} = -15 V,		11		
Turn-Off Delay Time	t _{d(off)}	$I_D = -3.5 A, R_G = 6 \Omega$		32		1
Fall Time	t _f			14		
Turn-On Delay Time	t _{d(on)}			9.0		ns
Rise Time	t _r	VGS = -4.5 V, VDS = -15 V.		16		1
Turn-Off Delay Time	t _{d(off)}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -15 \text{ V},$ $I_{D} = -3.5 \text{ A}, R_{G} = 6 \Omega$		25		1
Fall Time	t _f			22		1
DRAIN-SOURCE DIODE CHARACTERISTI	cs					
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_S = -1.0 \text{ A}, T_J = 25^{\circ}\text{C}$		-0.8	-1.2	V
Reverse Recovery Time	t _{RR}			14		ns
Charge Time	t _a	V _{GS} = 0 V, I _S = -1.0 A,		10		1
Discharge Time	t _b	$dl_{SD}/d_t = 100 A/\mu s$		4.0		1
Reverse Recovery Charge	Q _{RR}			8.0		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

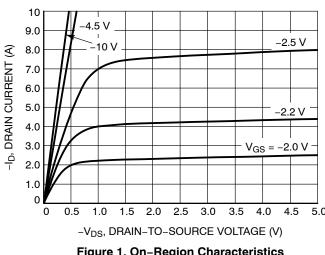
2. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%

- 4. Switching characteristics are independent of operating junction temperatures

10

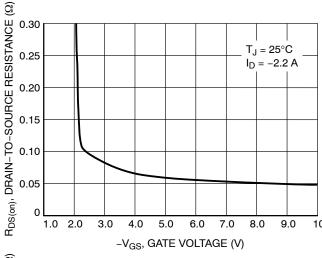
TYPICAL CHARACTERISTICS



9.0 $V_{DS} = -5 V$ -ID, DRAIN CURRENT (A) 8.0 7.0 6.0 5.0 4.0 $T_J = 25^{\circ}C$ 3.0 2.0 T_J = 125°C 1.0 2.75 1.0 1.25 1.5 1.75 2.0 2.25 2.5 -V_{GS}, GATE-TO-SOURCE VOLTAGE (V)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



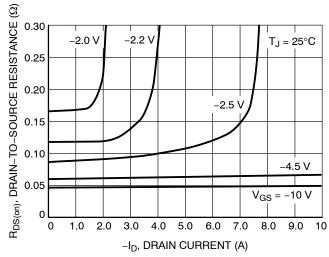
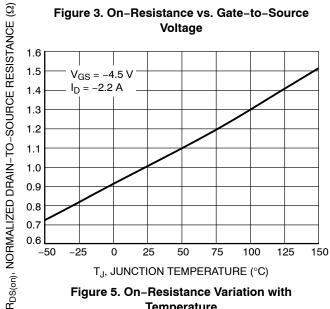


Figure 3. On-Resistance vs. Gate-to-Source Voltage

Figure 4. On-Resistance vs. Drain Current and **Gate Voltage**



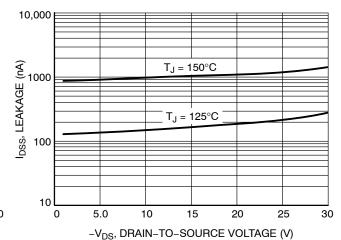


Figure 5. On-Resistance Variation with **Temperature**

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

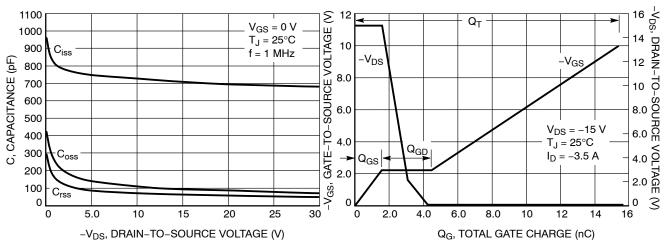


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

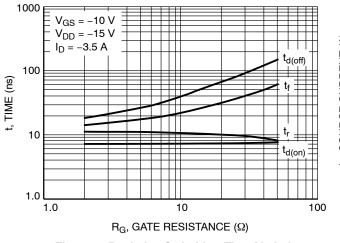


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

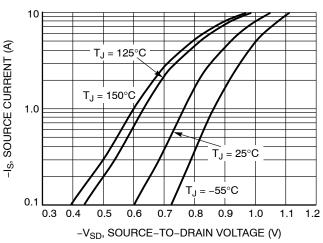


Figure 10. Diode Forward Voltage vs. Current

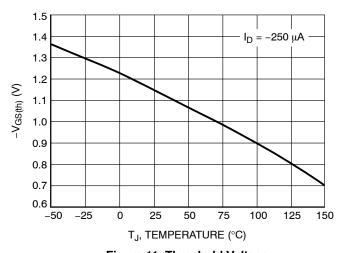


Figure 11. Threshold Voltage

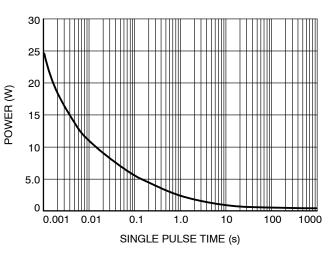


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS

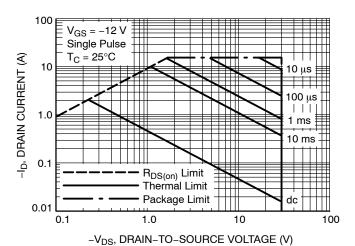


Figure 13. Maximum Rated Forward Biased Safe Operating Area

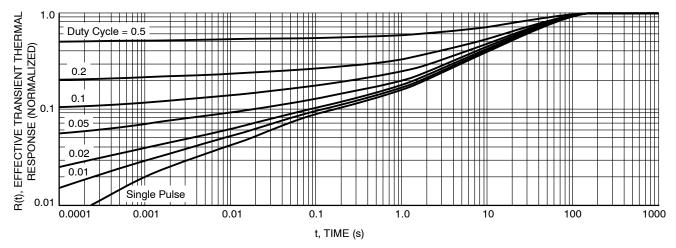


Figure 14. FET Thermal Response



MECHANICAL CASE OUTLINE

MILLIMETERS

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40

PACKAGE DIMENSIONS



SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

DATE 14 AUG 2024

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

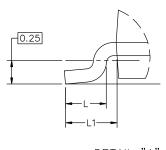
0.55

0.69

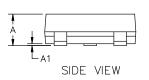
2.64

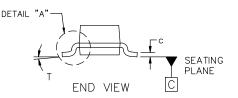
10°

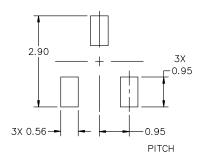




DETAIL "A" Scale 3:1







NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1.
- PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: STYLE 8: PIN 1. EMITTER PIN 1. ANOD 2. BASE 2. NO CC 3. COLLECTOR 3. CATHO	ONNECTION	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: STYLE 12: PIN 1. ANODE PIN 1. CATHO 2. CATHODE 2. CATHO 3. CATHODE-ANODE 3. ANODO	ODE 2. DRAIN 2. GATE	
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: STYLE 18: PIN 1. NO CONNECTION PIN 1. NO CO 2. ANODE 2. CATHO 3. CATHODE 3. ANODO	ODE 2. ANODE 2. ANODE	
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: STYLE 24: PIN 1. ANODE PIN 1. GATE 2. ANODE 2. DRAIN 3. CATHODE 3. SOURCE		CTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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